Gallium Nitride 28V 80W, RF Power Transistor

Description

The NU6008H is a 80W 28V, internally matched GaN HEMT, designed for multiple applications with frequencies up to 4GHz.

It can support pulse, CW at saturated condition or any modulation signal at backoff condition.

There is no guarantee of performance when this part is used in applications designed Outside of these frequencies.

•Typical performance (on Innogration 2.7-3.1GHz wideband fixture with device soldered)

VDS= 28V, Vpeak=-2.62V, Idq=150mA					
Freq (MHz)	P-1(dBm)	P-1Gain(dB)	P-3(dBm)	P-3(W)	Eff (%)
2700	49.75	13.1	50.39	109	55.8
2900	49.27	14.2	50.17	104	61.2
3100	48.64	13.3	49.75	94	63.6

Applications and Features

- Suitable for wireless communication infrastructure, wideband amplifier, EMC testing, ISM etc.
- · High Efficiency and Linear Gain Operations
- Thermally Enhanced Industry Standard Package

Important Note: Proper Biasing Sequence for GaN HEMT Transistors Turning the device ON

- 1. Set VGS to the pinch--off (VP) voltage, typically -5 V
- 2. Turn on VDS to nominal supply voltage (28V)
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level
- Table 1. Maximum Ratings (Not simultaneous, TC = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	150	Vdc
GateSource Voltage	V _{GS}	-10,+2	Vdc
Operating Voltage	Vdd	40	Vdc
Maximum Forward Gate Current	Igmax	18	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature(See note 1)	TJ	+225	°C

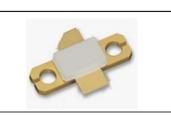
1. Continuous operation at maximum junction temperature will affect MTTF

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Rejc-dc	2.4	°C/W
T_c = 85°C, T_J =200°C, DC Power Dissipation(See note 1)		2.4	

ReJC-DC is tested at only DC condition, it is related to the highest thermal resistor value among all test conditions. It might be

differently lower in different RF operation conditions like CW signal ,pulsed RF signal etc.



- High Reliability Metallization Process
- Excellent thermal Stability and Excellent Ruggedness
- · Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

Turning the device OFF

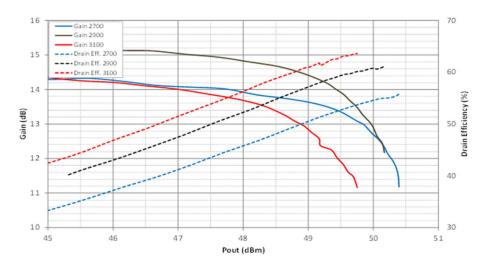
- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

Table 3. Electrical Characteristics (T_C = 25°C unless otherwise noted)

DC Characteristics

Characteristic Conditions		Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage V _{GS} =-8V; I _{DS} =18mA		V _{DSS}	150			V
Gate Threshold Voltage V _{DS} = 28V, I _D =18mA		V _{GS} (th)	-4	-	-2	V
Gate Quiescent VoltageVDS =28V, IDS =150mA, Measured in Functional Test		V _{GS(Q)}		-2.6		V
unctional Tests (In Innogration 1.60	Hz narrow band Test Fixture, 50	ohm system) :	V _{DD} = 28 Vdc,	I _{DQ} = 150 mA,	f = 3.1GHz, Pu	lsed CW
Characte	eristic	Symbol	Min	Тур	Max	Unit
Power Gain		Gp		11		dB
Drain Efficiency @ P _{SAT}	Eff	60			%	
Saturated Power	P _{SAT}	49			dBm	
Input Return Loss	ut Return Loss			-5		dB
Mismatch stress at all phases (Device	VSWR		10:1		Ψ	

Figure 1: Efficiency and power gain as function of Pout : Pulsed CW: 100us width , 10% duty cycle



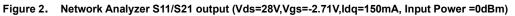
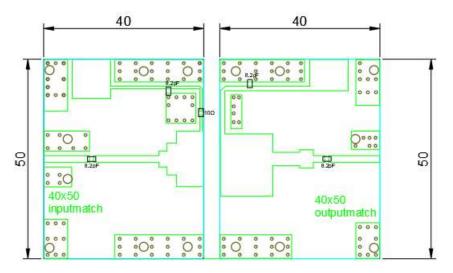




Figure 4: Picture of application board 2.7-3.1GHz class AB (PCB: 20 Mil Rogers 4350, Layout file upon request)



Package Outline

Flanged ceramic package; 2 leads

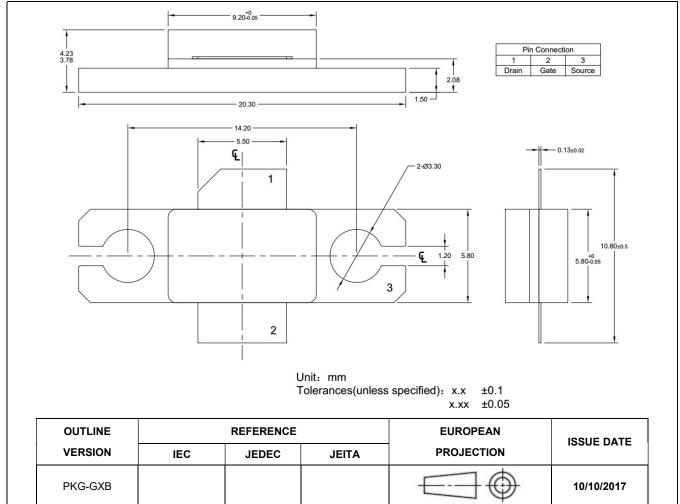


Figure 1. Package Outline PKG-G2E

Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status	
2021/6/11	V1.0	Preliminary Datasheet Creation	

Application data based on HJ-21-09

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